

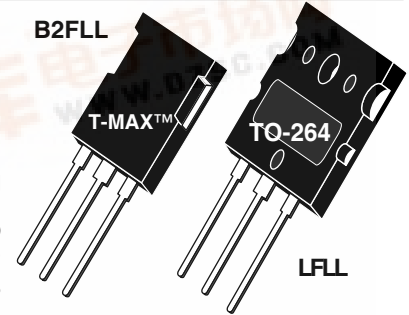


600V 54A 0.100Ω
 APT6010B2FLL APT6010LFLL
 APT6010B2FLL* APT6010LFLLG*

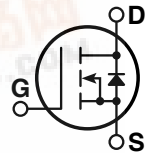
*G Denotes RoHS Compliant, Pb Free Terminal Finish.

POWER MOS 7[®] FREDFET

Power MOS 7[®] is a new generation of low loss, high voltage, N-Channel enhancement mode power MOSFETS. Both conduction and switching losses are addressed with Power MOS 7[®] by significantly lowering $R_{DS(ON)}$ and Q_g . Power MOS 7[®] combines lower conduction and switching losses along with exceptionally fast switching speeds inherent with Microsemi's patented metal gate structure.



- Lower Input Capacitance
- Lower Miller Capacitance
- Lower Gate Charge, Q_g
- Increased Power Dissipation
- Easier To Drive
- Popular T-MAX™ or TO-264 Package
- **FAST RECOVERY BODY DIODE**



MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	APT6010B2_LFLL	UNIT
V_{DSS}	Drain-Source Voltage	600	Volts
I_D	Continuous Drain Current @ $T_C = 25^\circ\text{C}$	54	Amps
I_{DM}	Pulsed Drain Current ^①	216	
V_{GS}	Gate-Source Voltage Continuous	±30	Volts
V_{GSM}	Gate-Source Voltage Transient	±40	
P_D	Total Power Dissipation @ $T_C = 25^\circ\text{C}$	690	Watts
	Linear Derating Factor	5.52	W/°C
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	°C
T_L	Lead Temperature: 0.063" from Case for 10 Sec.	300	
I_{AR}	Avalanche Current ^① (Repetitive and Non-Repetitive)	54	Amps
E_{AR}	Repetitive Avalanche Energy ^①	50	mJ
E_{AS}	Single Pulse Avalanche Energy ^④	3000	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV_{DSS}	Drain-Source Breakdown Voltage ($V_{GS} = 0V, I_D = 250\mu\text{A}$)	600			Volts
$R_{DS(on)}$	Drain-Source On-State Resistance ^② ($V_{GS} = 10V, I_D = 27A$)			0.100	Ohms
I_{DSS}	Zero Gate Voltage Drain Current ($V_{DS} = 600V, V_{GS} = 0V$)			100	μA
	Zero Gate Voltage Drain Current ($V_{DS} = 480V, V_{GS} = 0V, T_C = 125^\circ\text{C}$)			500	
I_{GSS}	Gate-Source Leakage Current ($V_{GS} = \pm 30V, V_{DS} = 0V$)			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage ($V_{DS} = V_{GS}, I_D = 2.5mA$)	3		5	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

DYNAMIC CHARACTERISTICS

APT6010B2_LFLL

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C _{iss}	Input Capacitance	V _{GS} = 0V V _{DS} = 25V f = 1 MHz		6710		pF
C _{oss}	Output Capacitance			1250		
C _{rss}	Reverse Transfer Capacitance			90		
Q _g	Total Gate Charge ③	V _{GS} = 10V V _{DD} = 300V I _D = 54A @ 25°C		150		nC
Q _{gs}	Gate-Source Charge			30		
Q _{gd}	Gate-Drain ("Miller") Charge			75		
t _{d(on)}	Turn-on Delay Time	RESISTIVE SWITCHING V _{GS} = 15V V _{DD} = 300V I _D = 54A @ 25°C R _G = 0.6Ω		12		ns
t _r	Rise Time			19		
t _{d(off)}	Turn-off Delay Time			34		
t _f	Fall Time			9		
E _{on}	Turn-on Switching Energy ⑥	INDUCTIVE SWITCHING @ 25°C V _{DD} = 400V, V _{GS} = 15V I _D = 54A, R _G = 5Ω		885		μJ
E _{off}	Turn-off Switching Energy			970		
E _{on}	Turn-on Switching Energy ⑥	INDUCTIVE SWITCHING @ 125°C V _{DD} = 400V, V _{GS} = 15V I _D = 54A, R _G = 5Ω		1150		
E _{off}	Turn-off Switching Energy			1220		

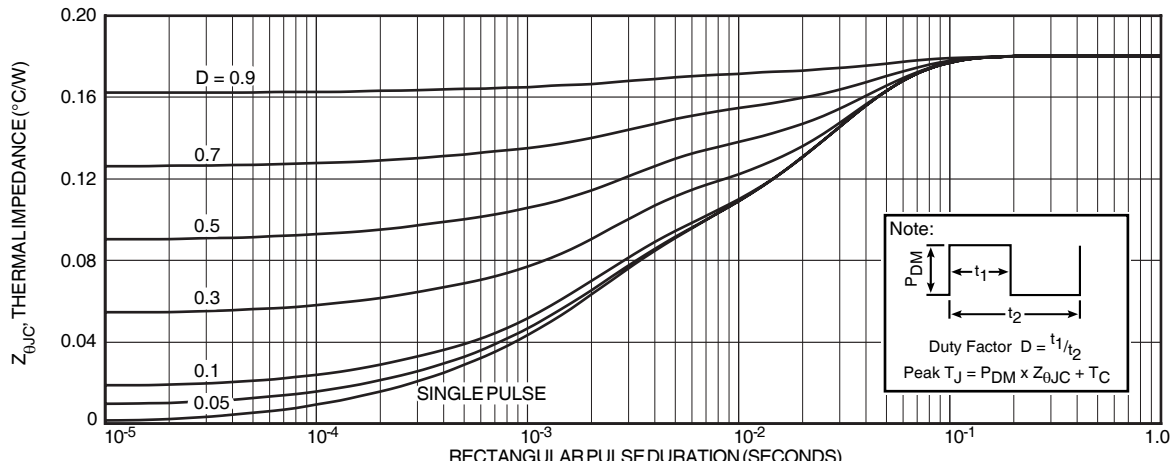
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I _S	Continuous Source Current (Body Diode)			54	Amps
I _{SM}	Pulsed Source Current ① (Body Diode)			216	
V _{SD}	Diode Forward Voltage ② (V _{GS} = 0V, I _S = -54A)			1.3	Volts
dv/dt	Peak Diode Recovery dv/dt ⑤			15	V/ns
t _{rr}	Reverse Recovery Time (I _S = -54A, di/dt = 100A/μs)	T _j = 25°C		300	ns
		T _j = 125°C		600	
Q _{rr}	Reverse Recovery Charge (I _S = -54A, di/dt = 100A/μs)	T _j = 25°C		2.7	μC
		T _j = 125°C		7.8	
I _{RRM}	Peak Recovery Current (I _S = -54A, di/dt = 100A/μs)	T _j = 25°C		14	Amps
		T _j = 125°C		20	

THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
R _{θJC}	Junction to Case			0.18	°C/W
R _{θJA}	Junction to Ambient			40	

- ① Repetitive Rating: Pulse width limited by maximum junction temperature
 - ② Pulse Test: Pulse width < 380 μs, Duty Cycle < 2%
 - ③ See MIL-STD-750 Method 3471
 - ④ Starting T_j = +25°C, L = 2.06mH, R_G = 25Ω, Peak I_L = 54A
 - ⑤ dv/dt numbers reflect the limitations of the test circuit rather than the device itself. I_S ≤ -I_D54A di/dt ≤ 700A/μs v_R ≤ 600V T_j ≤ 150°C
 - ⑥ Eon includes diode reverse recovery. See figures 18, 20.
- Microsemi reserves the right to change, without notice, the specifications and information contained herein.



Typical Performance Curves

APT6010B2FLL_LFLL

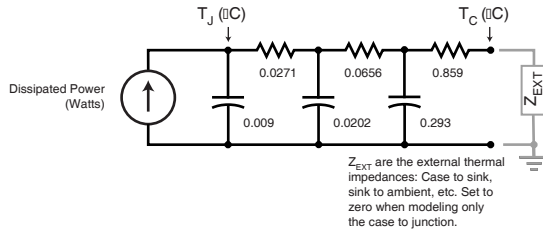


FIGURE 2, TRANSIENT THERMAL IMPEDANCE MODEL

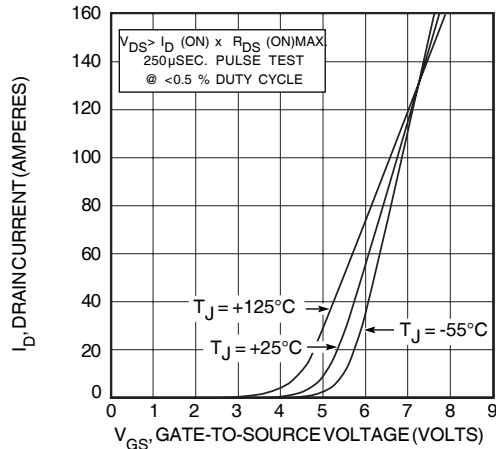


FIGURE 4, TRANSFER CHARACTERISTICS

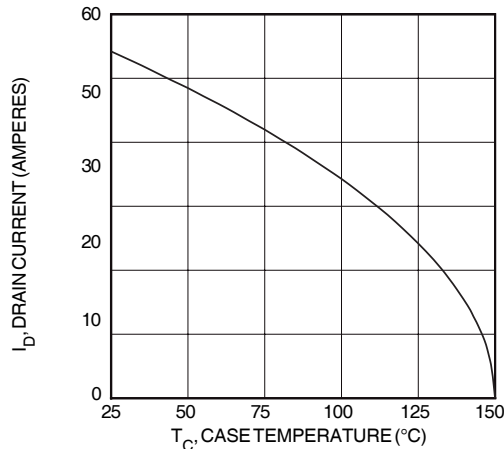


FIGURE 6, MAXIMUM DRAIN CURRENT vs CASE TEMPERATURE

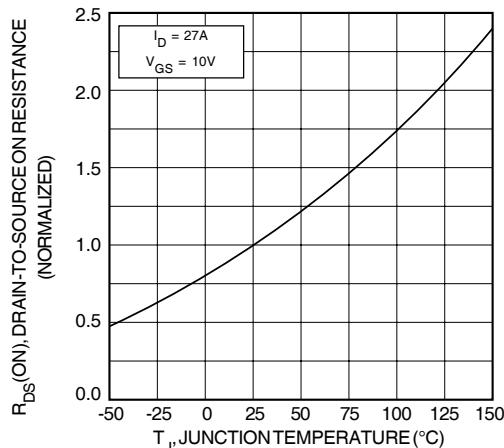


FIGURE 8, ON-RESISTANCE vs. TEMPERATURE

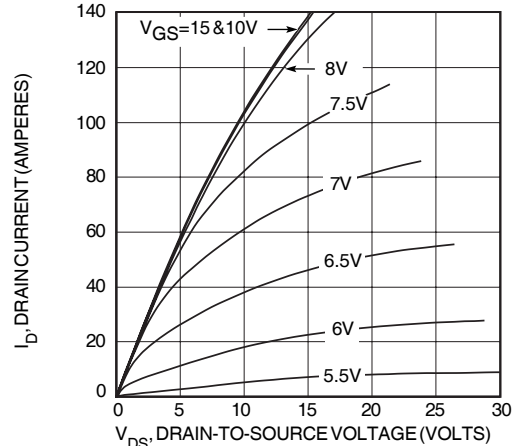


FIGURE 3, LOW VOLTAGE OUTPUT CHARACTERISTICS

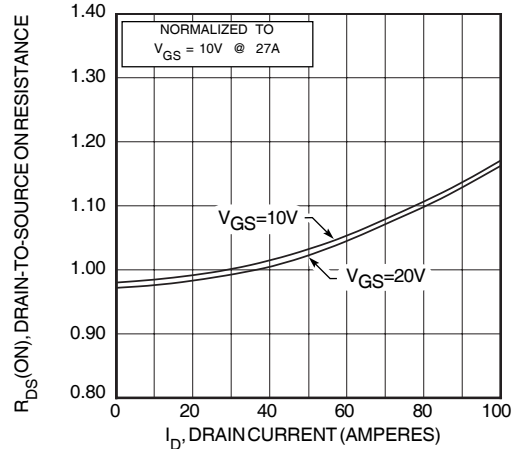


FIGURE 5, $R_{DS}(ON)$ vs DRAIN CURRENT

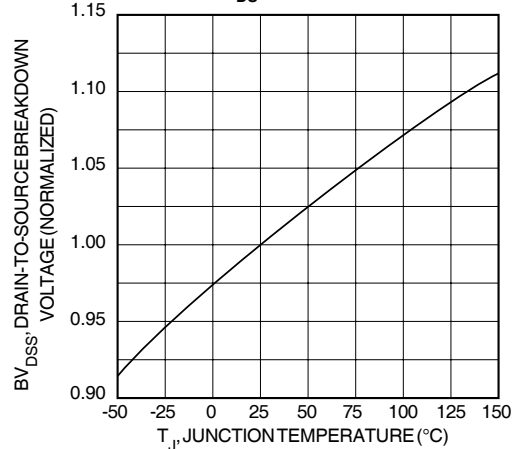


FIGURE 7, BREAKDOWN VOLTAGE vs TEMPERATURE

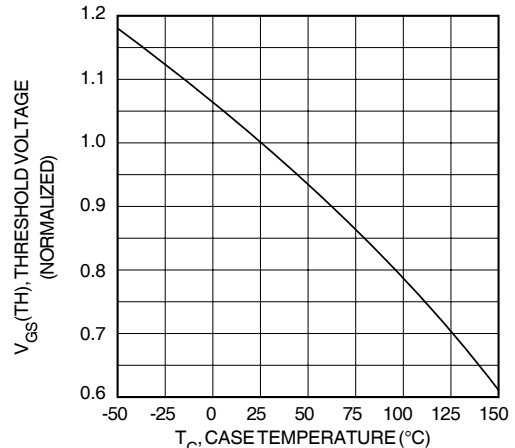


FIGURE 9, THRESHOLD VOLTAGE vs TEMPERATURE

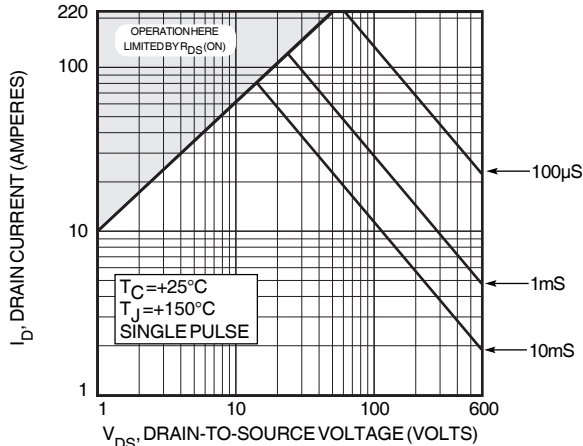


FIGURE 10, MAXIMUM SAFE OPERATING AREA

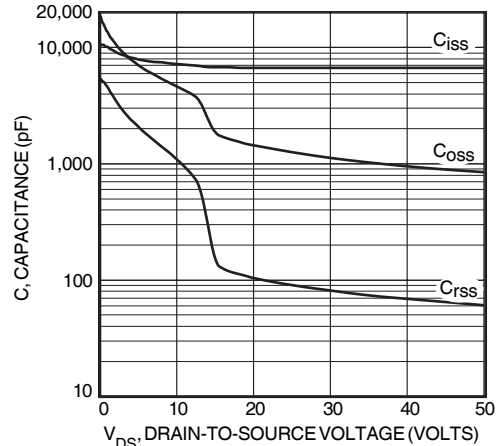


FIGURE 11, CAPACITANCE vs DRAIN-TO-SOURCE VOLTAGE

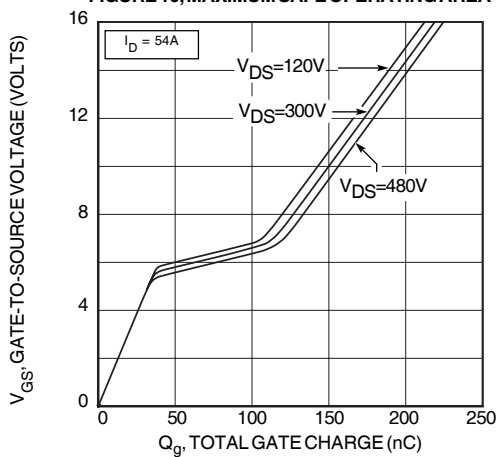


FIGURE 12, GATE CHARGES vs GATE-TO-SOURCE VOLTAGE

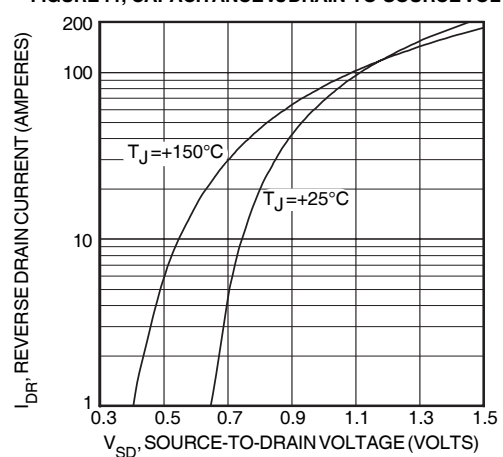


FIGURE 13, SOURCE-DRAIN DIODE FORWARD VOLTAGE

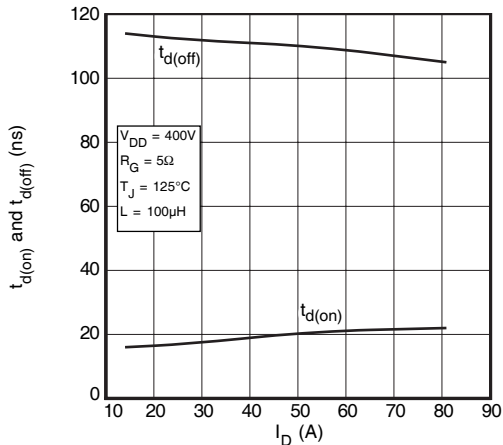


FIGURE 14, DELAY TIMES vs CURRENT

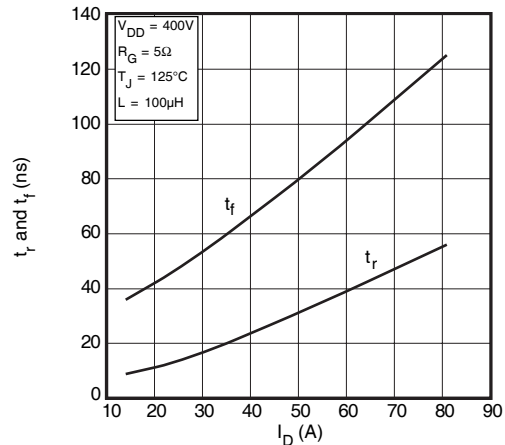


FIGURE 15, RISE AND FALL TIMES vs CURRENT

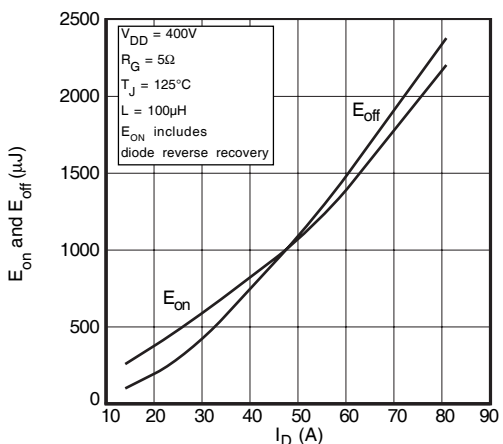


FIGURE 16, SWITCHING ENERGY vs CURRENT

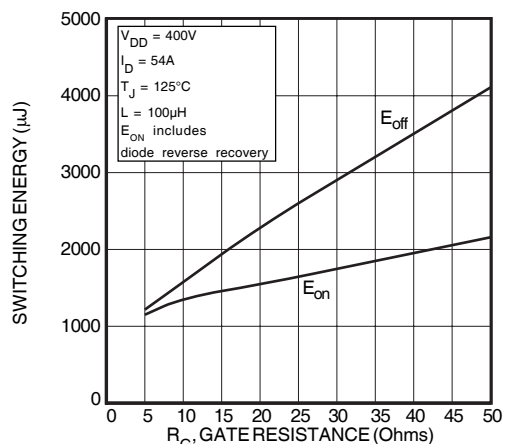


FIGURE 17, SWITCHING ENERGY vs. GATE RESISTANCE

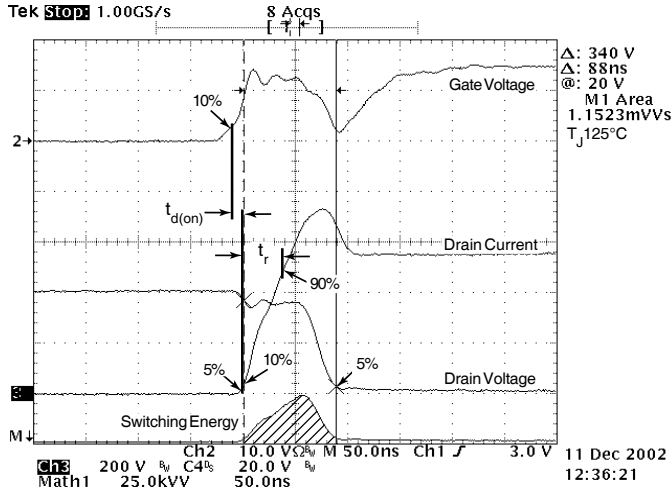


Figure 18, Turn-on Switching Waveforms and Definitions

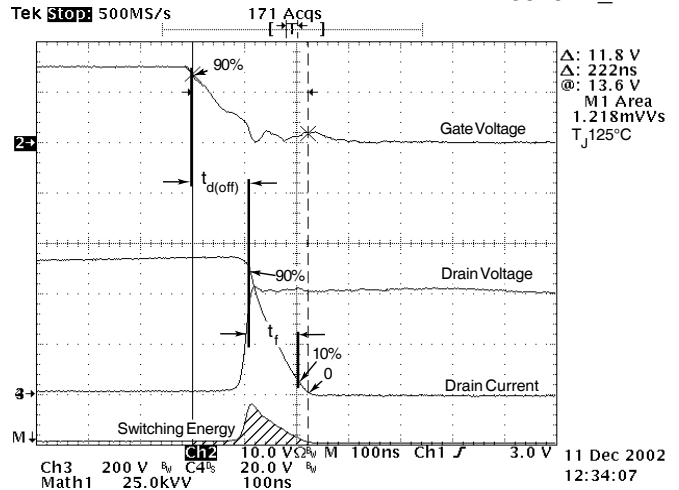


Figure 19, Turn-off Switching Waveforms and Definitions

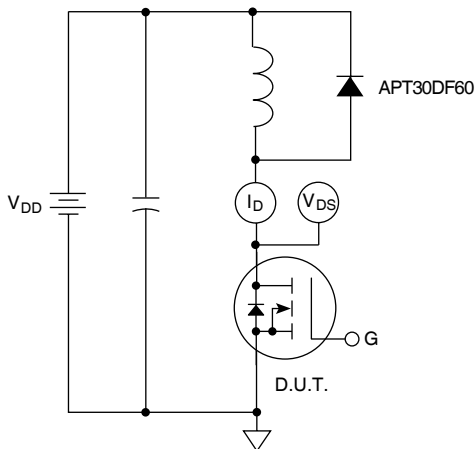
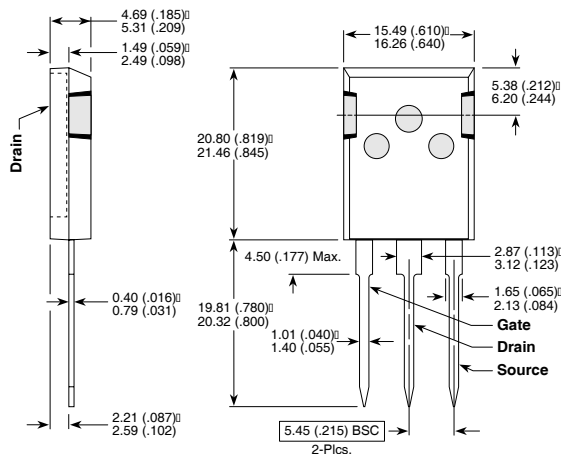


Figure 20, Inductive Switching Test Circuit

T-MAX™ (B2) Package Outline

(e1) SAC: Tin, Silver, Copper

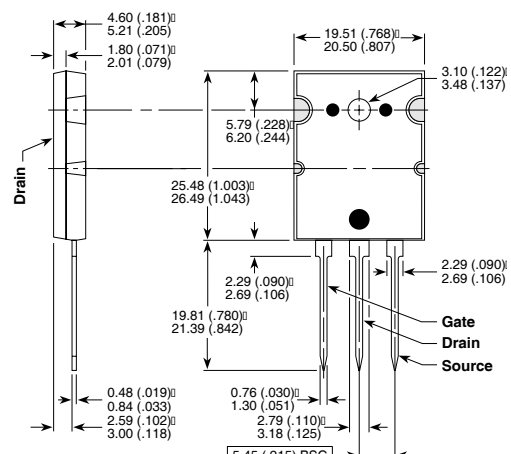


These dimensions are equal to the TO-247 without the mounting hole.

Dimensions in Millimeters and (Inches)

TO-264 (L) Package Outline

(e1) SAC: Tin, Silver, Copper



Dimensions in Millimeters and (Inches)